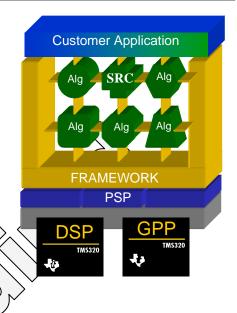


- eXpressDSP™ compliant
- Supports sampling frequency conversion from any to any frequency within the standard set (8, 11.025, 16, 22.05, 24, 32, 44.1, 48) KHz



description

- Efficient Stereo SRC implementation on a single MS320C55x DSP
- Supported Sampling Frequencies (KHz): 8, 11.025, 12, 16, 22.05, 24, 32, 44.1, 48
- 16th Order Lagrange Interpolation for upward conversion
- 2nd Order Low pass Elliptic Filter to reduce aliasing
- 16th Order Lagrange Interpolation for downward conversion
- TI eXpressDSP compliant.
- Fully validated on TMS320C5510 EVM using CCS ver 2.2 with the code generation tools version 2.56.



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Summary of performance

Table 1. **Configuration Table**

CONFIGURATION	ID
For Sampling Rate Conversion from 44.1KHz to 48.0KHz	А

Table 2. Cycles Information - Profiled on TMS320C5510 EVM with CCS 2.2/ cgtools 2.56

CONFIGURATION ID	TEST FILE PARAMETERS	PERFORMANCE STATISTICS (IN MEGACYCLES /SEC) ¹	
		AVERAGE	PEAK
А	Sampling Frequency 44.1 KHz	6,852	7.876

Table 3. Memory Statistics - Generated with Code Generation Tools Version 2.56

	MEMORY STATISTICS ²				
CONFIGURATION	PROGRAM DATA MEMORY		TOTAL		
	MEMORY	INTERNAL	EXTERNAL	STACK	TOTAL
A	2.515	2.929	0	0.500	5.944

² All memory requirements are expressed in kilobytes (1 kilobyte = 1024 8-bit bytes).

Table 4. Internal Data Memory Split-up

	DATA MEMORY – INTERNAL ²		
CONFIGURATION	SHARED		INSTANCE ³
	CONSTANTS	SCRATCH	INSTANCE
	2.343	0	0.586

² All memory requirements are expressed in kilobytes (1 kilobyte = 1024 8-bit bytes) ³ Does not include I/O byters



PRODUCT PREVIEN

notes

• I/O Buffers - Input Buffer Size = 64 bytes, Output Buffer Size = 128 bytes.

Total Data Memory for N Non-Pre-Emptive Instances =

Constants + Runtime Tables + Scratch + N*(Instance + I/O buffers + Stack)

• Total Data Memory for N Pre-Emptive Instances =

Constants + Runtime Tables + N*(Instance + I/O buffers + Stack + Scratch)

Stack includes stack and sysstack

references

Texas Instruments "SRC reference Manual"

glossary

Constants Elements that go into .const memory section

Scratch Memory space that can be reused across different instances of the algorithm

Shared Sum of Constants and Scratch

Instance Persistent-memory that contains persistent information - allocated for each

instance of the algorithm.

acronyms

SRC Sample Rate Converter





REVISION HISTORY

Scope: Applicable updates to the Sample Rate Converter on TMS320C55xx EVM have been incorporated.

DATE	VERSION	ADDITIONS/CHANGES/DELETIONS
22 ND May 03	V1.0	Initial
28 TH May 03	V1.1	Review Comments Incorporated
28 [™] Jan 04	V1.2	Updated the template
		(0/1)



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